Picture it: DSPs in medical imaging

TEXAS INSTRUMENTS





TI has an extensive portfolio of products for numerous health care applications. Among these are TI's digital signal processors (DSPs), which are well suited to meet the intensive processing needs demanded by medical-imaging applications. These DSPs are inherently software programmable, which provides several key benefits in the medical-imaging space. Chief among these is the ability to upgrade existing equipment in the field via a software load. This provides a solid level of future-proofing by enabling upgrades and improvements to product functionality without having to redo any hardware. Software programmability also aides in development and implementation of new, advanced algorithms on existing equipment or development hardware, thus speeding up time-to-market and return on investment.

The combination of high performance and low power consumption makes DSPs ideal for a range of imaging applications, from real-time surgical imaging equipment to portable handheld devices. The high-performance processing of DSPs adds real-time capability required by many medical-imaging modalities. The low power consumption of DSPs minimizes battery size, and consequently product size, enabling medical-imaging applications in portable form factors.

TI offers several devices based on the innovative KeyStone[™] multicore architecture that leverage TI's TMS320C66x DSP generation, the fastest integrated fixed- and floating-point DSP core available today. In addition to having the highest GMACS and GFLOPS per watt of any programmable high-performance core in the industry, the C66x DSPs are fully backward compatible with all existing TMS320C6000[™] power-efficient DSPs, allowing for maximum reuse from previous platforms.

The **TMS320C667x family** of devices offers pin- and software-compatible platforms that allow scaling from one, two, four and eight DSP core devices to meet a range of processing requirements. Each C667x DSP can deliver 40 GMACS/20 GLFOPS of processing performance at 1.2 GHz and includes 512-KB local L2 per core and large shared L2 on-chip cache for image manipulation and processing. The C667x DSPs also feature high-bandwidth I/O including two lanes of v2 PCle and four lanes of v2 Serial RapidIO[®] (SRIO) providing processor-to-processor communication at up to 5 Gbaud per lane full-duplex. The family also supports $4 \times$ HyperLink with up to 12.5-Gbaud lane rate and $2 \times$ SGMII Ethernet ports. These interfaces make multiprocessing architectures easier to implement, eliminating the need for external interface bridge devices and lowering overall system cost.

With up to 10GHz of total processing power, the eight-core **TMS320C6678 DSP** is wellsuited for complex imaging applications. The C6678 DSP has up to 320 GMACS/160 GFLOPS of processing performance at 1.2 GHz and includes 4-MB shared L2 on-chip cache for image manipulation and processing. The TMS320C665x DSP generation fits well in portable and power-constrained medical imaging applications like portable ultrasound systems. Optimized for power efficiency, the dual-core **TMS320C6657 DSP** running at 1 GHz delivers 64 GMACS/32 GFLOPS at 3.5W, while the single-core **TMS320C6654 DSP** can consume as little as 2W at 850 MHz.

For medical-imaging applications that require RISC processing, TI's **66AK2Hxx family** of DSP+ARM[®] system-on-chip (SoC) processors are designed to reduce development costs and time-to-market. These 28-nm devices based on the second generation of TI's KeyStone[™] architecture integrate TI's C66x DSPs with multiple ARM Cortex[™]-A15 MPCore[™] processors, facilitating the development of a wide-range of medical-imaging applications. The unique combination of Cortex-A15 processors and C66x DSPs, with built-in packet processing and Ethernet switching, is designed to efficiently offload and enhance the growing number of connected applications in the medical imaging space.

All these devices benefit from TI's development tools and runtime software support that makes migration and development simpler than ever. TI's free **Multicore Software Development Kit (MCSDK)** incorporates core software building blocks including platform software, a real-time operating system (SYS/BIOSTM), open source Linux operating system, low-level drivers, high-level APIs and optimized algorithm libraries, all in one package. Out-of-box demonstration applications and preloaded example projects that are included in the MCSDK and provide a quick start for developers creating new medical-imaging applications on TI's KeyStone devices.

Important Notice: The products and services of Texas Instruments Incorporated and its subsidiaries described herein are sold subject to TI's standard terms and conditions of sale. Customers are advised to obtain the most current and complete information about TI products and services before placing orders. TI assumes no liability for applications assistance, customer's applications or product designs, software performance, or infringement of patents. The publication of information regarding any other company's products or services does not constitute TI's approval, warranty or endorsement thereof.

The platform bar, KeyStone, SYS/BIOS and TIMS320C6000 are trademarks of Texas Instruments. All other trademarks are the property of their respective owners.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2013, Texas Instruments Incorporated